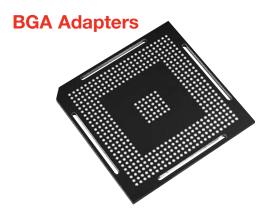
# Ball Grid Array (BGA) Adapters

5 Energy Way, P.O. Box 1019, West Warwick, RI 02893 USA Tel. 800-424-9850/401-823-5200 • Fax 401-823-8723 • Email info@advintcorp.com • Internet http://www.advintcorp.com



### Features:

- Soldering BGA Device to adapter subjects BGA to less thermal stress than soldering BGA directly to a PCB due to the adapter's lower mass.
- · Uses same footprint as BGA device.
- Custom adapters available for heat sink attachment.

#### **Terminals:**

Brass - Copper Alloy (C36000), ASTM-B-16

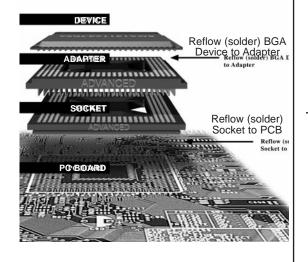
#### **Plating:**

G - Gold over Nickel

#### **Body Material:**

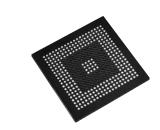
FR-4 Glass Epoxy, U.L. Rated 94V-O

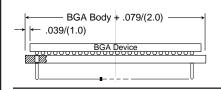
## **How It Works:**



# **Standard Adapter (A):**

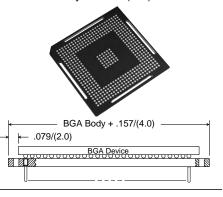
- Mates with Standard Socket (S)
- Adapter size equals BGA Device body + .079/(2.0)





# **Extraction Slot Adapter (AX):**

- Slots allow AIC extraction tool (sold separately) to easily remove device/ adapter assembly from socket.
- Mates with Extraction Socket (SB) or Guide Post Socket (SG)
- Adapter size equals the BGA Device body + .157/(4.0)



# **BGA Adapter Extraction Tool:**

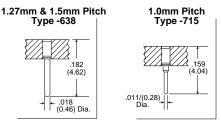
- Insert "T" bar end of tool into extraction slot adapter.
- · Slide tool to end of slot and pry adapter from socket.
- Repeat in additional slots until adapter is separated from socket.

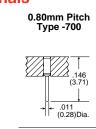


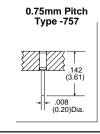


	Device Package Size	
	< 1.024 (26mm)	> 1.024 (26mm)
Tool P/N	5566	5504
Blade Width	.373/(9.5mm)	.675/(17.1mm)

**Terminals** 







## **How To Order**

